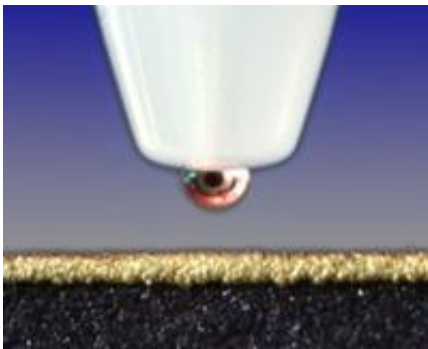


## TPT-application 33 $\mu$ copper bonding

### Equipment:

- 33 $\mu$  gold wire, 100m at 2" spool
- 33 $\mu$  copper capillary and 33 $\mu$  gold wedge
- Semiautomatic Wire Bonder HB16



capillary



ball bonding



wedge bonding

### Ball Bonding process:

- it is important that the N<sup>2</sup> gas is on the tool during the EFO (TPT Copper Kit Option H47)
- need more Bond Force like Gold wire
- otherwise same process like Gold bonding.
- it is recommended to heat up bond surface up to 120°C.

### Wedge Bonding process:

- need more Bond Force like Gold wire
- same process like Gold bonding.
- it is recommended to heat up bond surface up to 120°C.

### Advantages over gold bonding:

- cheaper wire in mass production.
- better electronically conductivity.
- better thermal conductivity.

